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 Derwent World Patents Index  
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### Search History

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**DATE:** Wednesday, April 20, 2005 [Printable Copy](#) [Create Case](#)

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microelectronic\$1 SAME packag\$3 SAME (support\$3 or substrate\$1)

<u>L6</u>	SAME (dies or singulat\$4 or separat\$3 or isolat\$3)	395	<u>L6</u>
<u>L5</u>	microelectronic\$1 SAME packag\$3 SAME (support\$3 or substrate\$1) SAME (barrier\$1 or encapsulat\$3)	338	<u>L5</u>
<u>L4</u>	microelectronic\$1 SAME packag\$3 SAME (support\$3 or substrate\$1) SAME (wire-bond\$3 or bond-wir\$3)	27	<u>L4</u>
<u>L3</u>	microelectronic\$1 SAME packag\$3 SAME (support\$3 or substrate\$1) SAME (circuit\$4 or adhesive\$1 or contact\$3 or trace\$1 or pad\$1)	1687	<u>L3</u>
<u>L2</u>	microelectronic\$1 SAME packag\$3 SAME (support\$3 or substrate\$1) SAME (dies or singulat\$4)	154	<u>L2</u>
<u>L1</u>	microelectronic\$1 SAME packag\$3 SAME (respons\$5 or active\$2)	463	<u>L1</u>

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